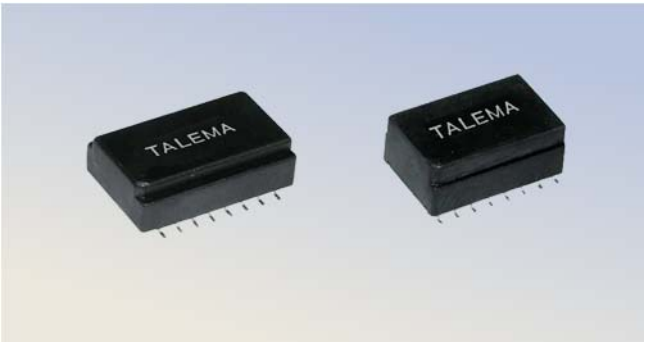
ISDN S_o Compact SMD Interface Modules

Features

- excellent output characteristics ensure compliance with CCITT.I.430 pulse waveform template when used with recommended IC pairing
- SMD modules are designed for pick and place compatability
- excellent and consistent balance between windings
- modular design maximizes suppression effectivity and transmission properties
- compact module eliminates three components reducing assembly and storage cost
- full compatibility with all common IC's
- operating temperature: 0 to 70°C



Electrical Specifications @ 25°C

Turns Ratio: **Bold** = IC side windings

Compact SMD Modules comply with Basic Insulation Level EN60950, UL1950 and UL1459

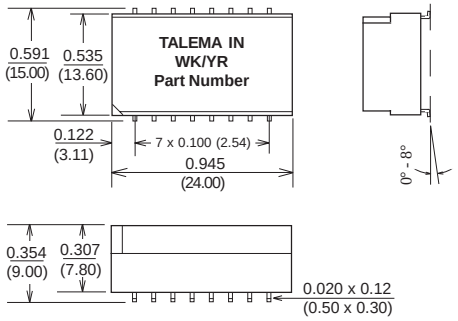
Part Number	L_P (mH Min)	Turns Ratio	L_L (µH Max)	ΔI_{DC} (mA)	C_C (pF Max)	$R_{CU}P$ (Ohms)	$R_{CU}S$ (Ohms)	V_P (Vrms)	Schematic
MSJ-400A-XXX	30	1:1:**1:1**	10	4	150	1.7	2.0	1500	A
MSJ-403A-XXX	30	1:1:**2:2**	10	4	150	1.7	4.0	1500	A
MSJ-405A-XXX	30	1:1:**2.5:2.5**	10	4	150	1.7	4.6	1500	A
MAJ-400A-XXX	30	1:1:**1:1**	5	4	120	1.7	1.7	1500	A
MAJ-403A-XXX	30	1:1:**2:2**	5	4	120	1.7	3.4	1500	A
MAJ-405A-XXX	30	1:1:**2.5:2.5**	5	4	120	1.9	4.4	1500	A

Common Mode Choke		
Basic P/N + Suffix (Example: MSJ-403A-470	L_N (µH)	R_{CU} (Ohms)
-000	No Choke	
-470	47	0.5
-101	100	0.7
-501	500	0.5
-502	5000	2.0

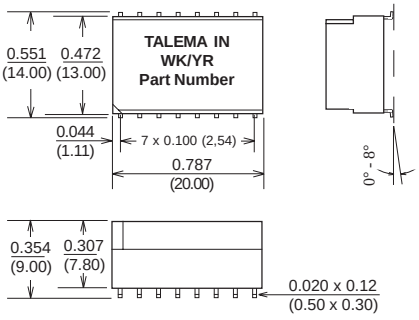
Test Conditions:
Inductance and coupling capcitance: 10kHz, 100mV
Common Mode Choke Inductance: 100kHz, 20mV
Leakage Inductance: 100kHz, 100mV

Standard Packaging: Tape and Reel

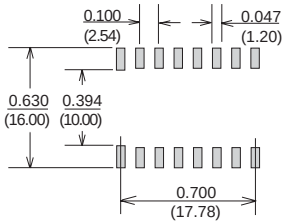
MSJ Module



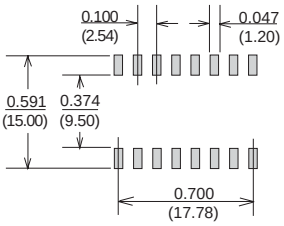
MAJ Compact Chip Module



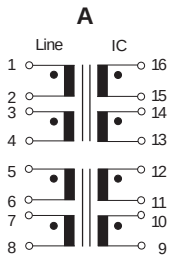
Suggested Pad Layout
MSJ



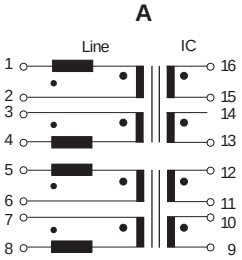
MAJ



Schematic - No Choke



Schematic - With Choke



Surface Coplanarity will be 0.004(0.10) maximum

Dimensions: Inches (Millimeters)
Tolerance: ±0.010 (0.25) unless specified otherwise